µClamp3311ZV

µClamp®

1-Line ESD & Surge Protection

PROTECTION PRODUCTS

Description

µClamp®series are designed to protect sensitive electronics from damage or latch-up due to ESD. They feature large cross-sectional area junctions for conducting high transient currents. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

µClamp3311ZV is in a 2-pin SLP1006P2X3F package, measuring1.0 x 0.6 x 0.25mm. Leads are spaced at a pitch of 0.65mm and are finished with lead-free NiAu. Each device will protect one bi-directional line operating at ±3.3 volts. µClamp3311ZV features extremely good protection characteristics highlighted by high surge current capability (80A, tp = 8/20µs), low peak ESD clamping voltage, and high ESD withstand voltage (± 30kV per IEC 61000-4-2). The combination of small size and high ESD & surge capability makes them ideal for use in applications like audio lines, battery protection and VBUS protection in portable devices such as cellular phones.

Features

- High ESD withstand Voltage: ±30kV (Contact) and ±30kV (Air) per IEC 61000-4-2
- High peak pulse current capability: 80A (tp = 8/20µs)
- Ultra-small package(1.0 x 0.6 x 0.25mm)
- Protects one I/O or power line
- Low ESD clamping voltage
- Working voltage: ± 3.3V
- Solid-state silicon-avalanche technology

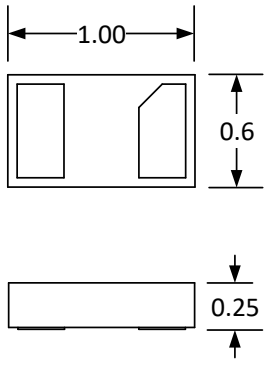
Mechanical Characteristics

- SLP1006P2X3F package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Molding compound flammability rating: UL 94V-0
- Lead Finish: NiAu
- Marking: Marking code
- Packaging: Tape and Reel

Applications

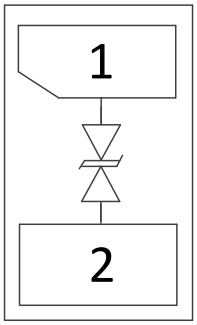
- Cellular Handsets & Accessories
- Battery Protection
- Notebooks & Handhelds
- USB Voltage Bus
- Audio lines

Package Dimension



Nominal Dimensions (mm)

Schematic & Pin Configuration



SLP1006P2X3F (Bottom View)

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (t_p = 8/20µs)	P_{PK}	580	W
Peak Pulse Current (t_p = 8/20µs)	I_{PP}	80	A
ESD per IEC 61000-4-2 (Air)(1) ESD per IEC 61000-4-2 (Contact)(1)	V_{ESD}	±30 ±30	kV
Operating Temperature	T_{OP}	-55 to +85	^{O}C
Storage Temperature	T_{STG}	-55 to +150	^{O}C

Electrical Characteristics (T=25^{O}C unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	Pin 1 to 2 or 2 to 1				3.3	V
Reverse Breakdown Voltage	V_{BR}	I_{BR}= 1mA, Pin 1 to 2 or 2 to 1		3.8	4.9	6.0	V
Reverse Leakage Current	I_R	V_{RWM} = 3.3 V, Pin 1 to 2 or 2 to 1			<10	100	nA
Clamping Voltage	V_C	t_p = 8/20µs, Pin 1 to 2 or 2 to 1	I_{PP}=10A		4	5.4	V
			I_{PP}=40A		4.8	6.3	
			I_{PP}=80A		6.2	7.3	
ESD Clamping Voltage[2]	V_C	tp=0.2/100ns	I = 4A		3.7		V
			I = 16A		3.71		
Dynamic Resistance[2,3]	R_{DYN}	tp = 0.2/100ns			<0.01		Ω
Junction Capacitance	C_J	V_R = 0V, f = 1MHz			81	100	pF

Notes:

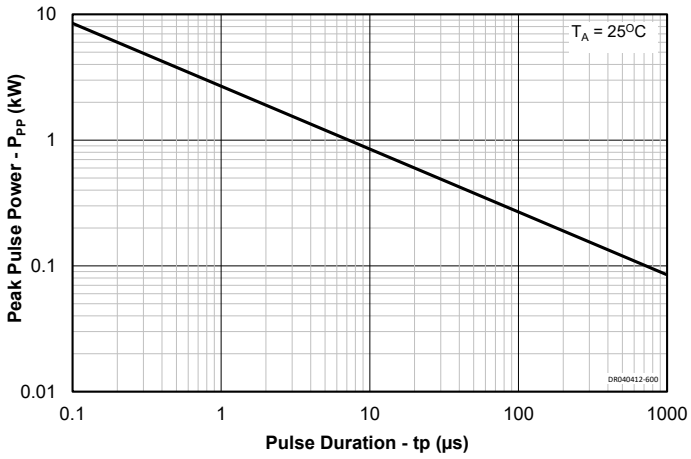
1) ESD gun return path connected to ESD ground plane.

2) Transmission Line Pulse Test (TLP) Settings: t_p = 100ns, t_r = 0.2ns, I_{TLP} and V_{TLP} averaging window: t_1 = 70ns to t_2 = 90ns

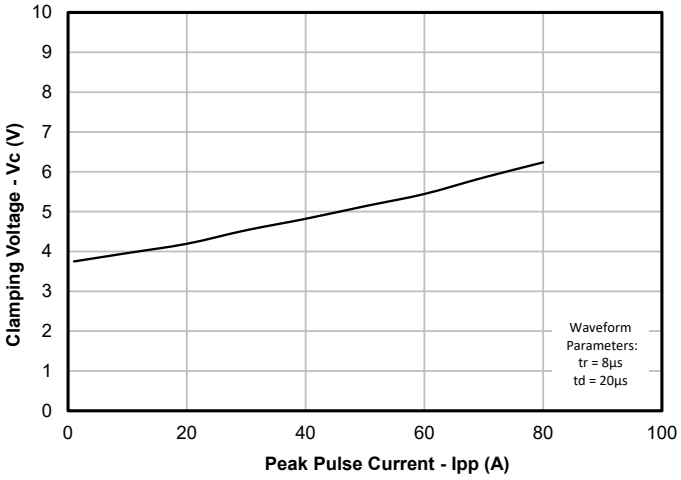
3) Dynamic resistance calculated from I_{TLP} = 4A to I_{TLP} = 16A

Typical Characteristics

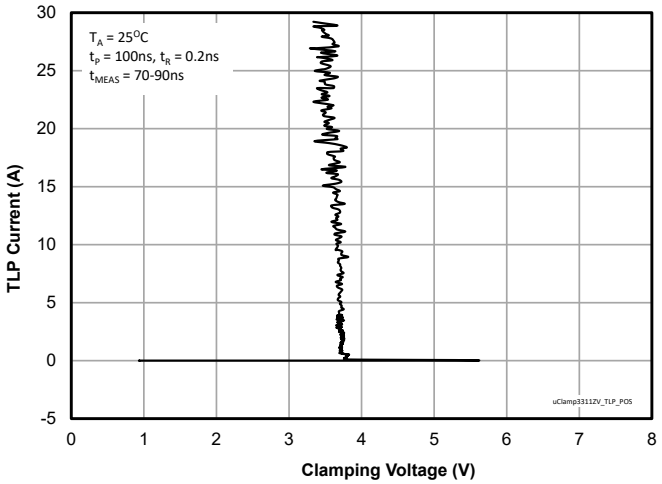
Non-Repetitive Peak Pulse Power vs. Pulse Time



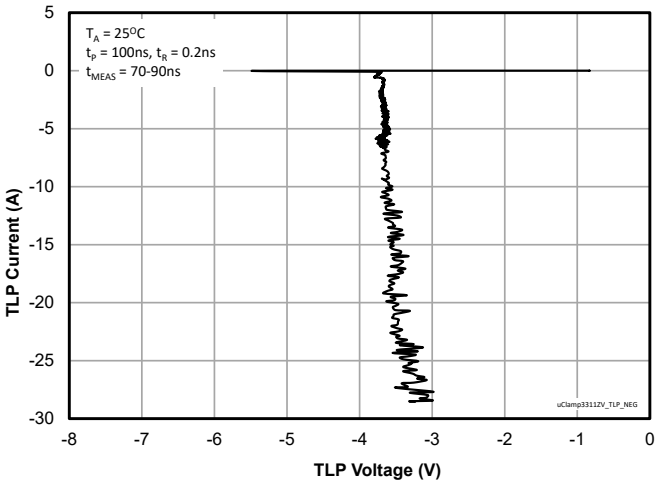
Clamping Voltage vs. Peak Pulse Current (t_p=8/20µs)



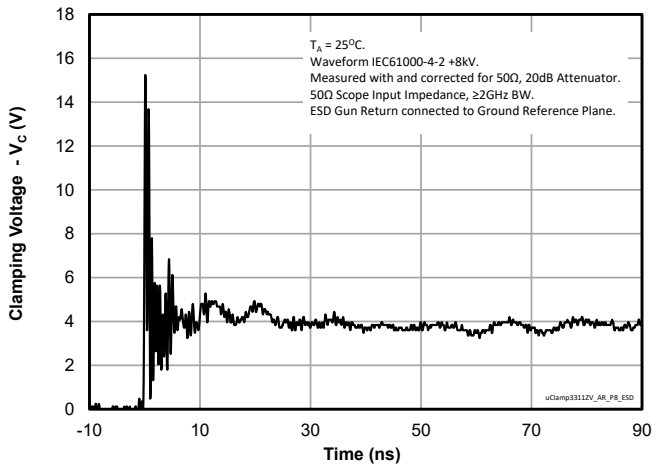
TLP Characteristic (Positive)



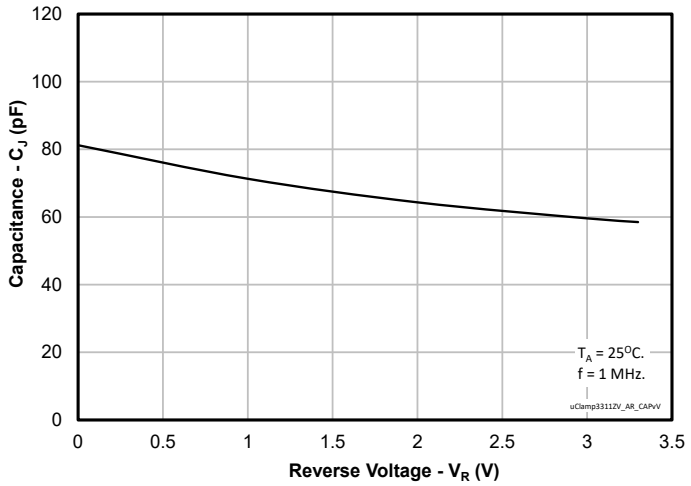
TLP Characteristic (Negative)



ESD Clamping (+8kV Contact per IEC 61000-4-2)



Capacitance vs. Voltage



Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. A minimum area ratio of 0.66 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W)/ (2 * (L + W) * T)

Where:
L = Aperture Length
W = Aperture Width
T = Stencil Thickness

Semtech recommends a stencil with square aperture and rounded corners for consistent solder release. The stencil should be laser cut with electro-polished finish. A stencil thickness of 0.100mm (0.004") or 0.125mm (0.005") stencil may be used, however the stencil opening may need to be increased slightly to achieve the desired area ratio to ensure proper solder coverage on the pad.

Recommended Mounting Pattern

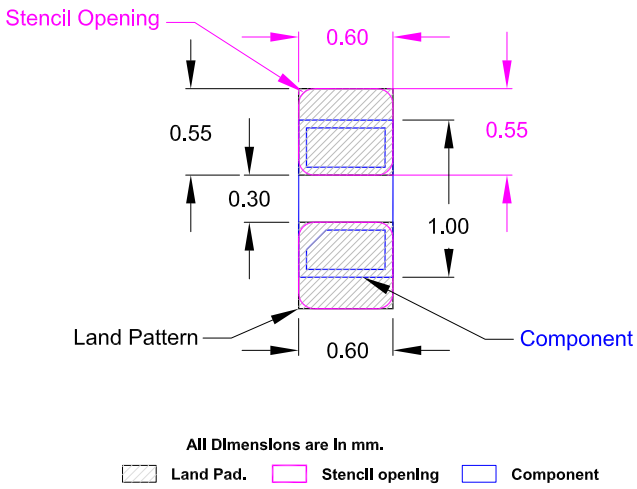
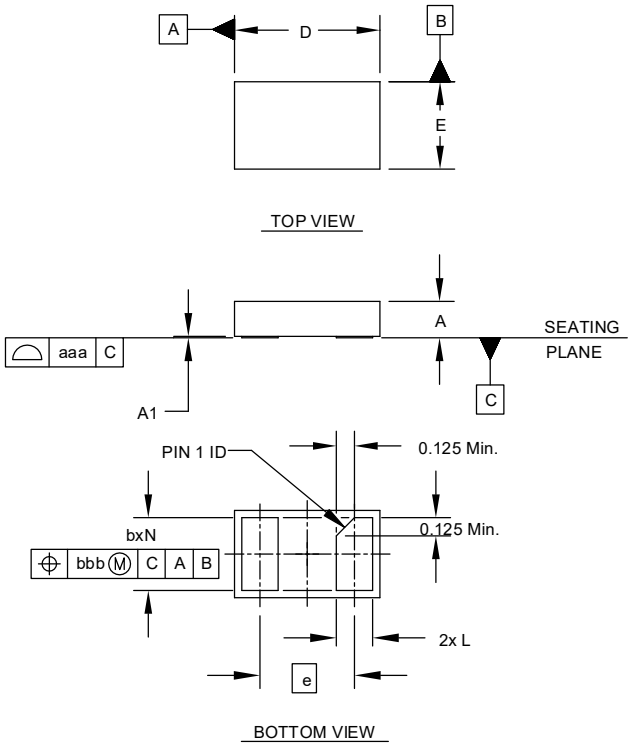


Table 1 - Assembly Guidelines

Assembly Parameter	Recommendation
Solder Stencil Design	Laser Cut, Electro-Polished
Aperture Shape	Rectangular with Rounded Corners
Solder Stencil Thickness	0.100mm (0.004") or 0.125mm (0.005")
Solder Paste Type	Type 4 or Type 5
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	SMD or NSMD
PCB Pad Finish	OSP or NiAu

Outline Drawing - SLP1006P2X3F

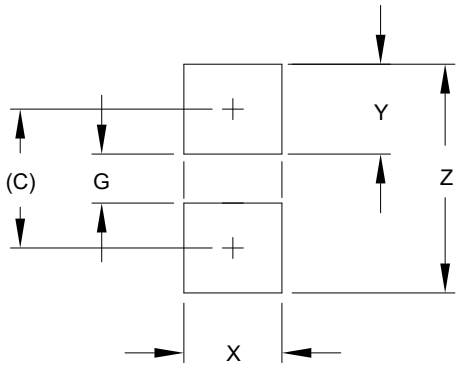


DIMENSIONS			
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.235	0.250	0.265
A1	0.00	0.010	0.050
b	0.45	0.50	0.55
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	0.65 BSC		
L	0.20	0.25	0.30
N	2		
aaa	0.08		
bbb	0.10		

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP1006P2X3F

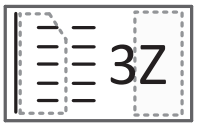


DIMENSIONS	
DIM	MILLIMETERS
C	(0.85)
G	0.30
X	0.60
Y	0.55
Z	1.40

NOTES:

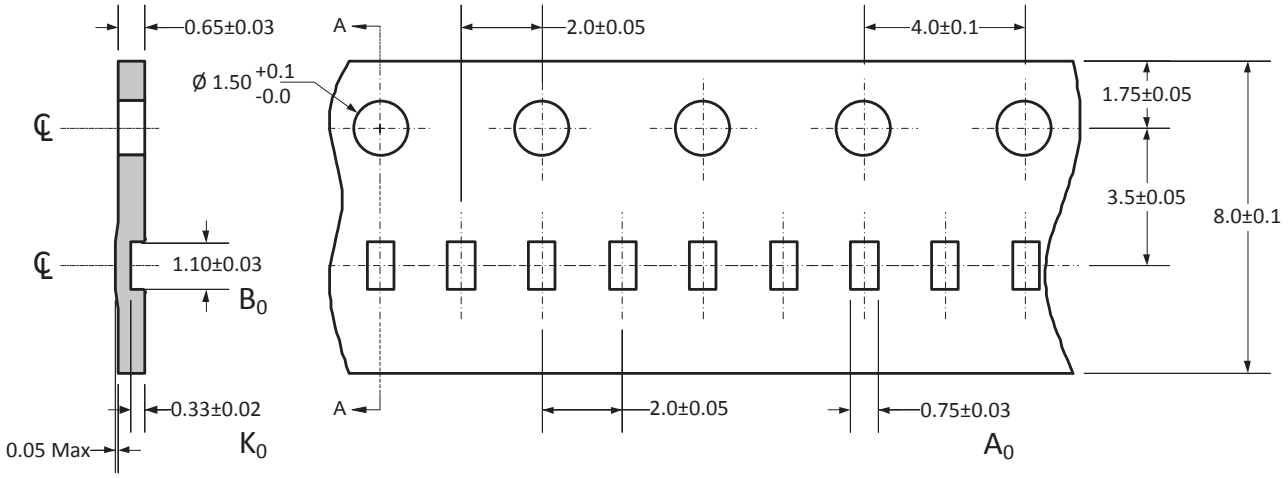
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

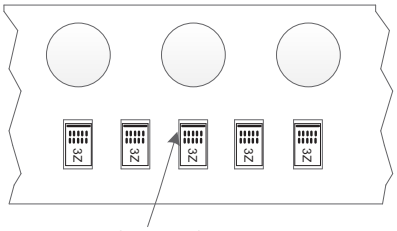
Marking Code



Notes:
1. Marking will also include line matrix date code.
2. Bar indicates Pin 1 location.

Tape and Reel Specification





Ordering Information

Part Number	Qty per Reel	Reel Size
µClamp3311ZVTFT	15,000	7″

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